SGM4891
1.2W Audio Power Amplifier

GENERAL DESCRIPTION

The SGM4891 is a 1.2W, fully integrated, audio power amplifier. It is designed to maximize audio performance in portable applications such as mobile phone. The portable application requires audio power amplifier has minimum of external components and can operate from a single 2.5V to 5.5V power supply. SGM4891 is capable of delivering 1.2W of continuous output power with typically 1% distortion (THD+N) when it drives an 8Ω speaker from a 5.0V power supply.

The SGM4891 features a low power consumption shutdown mode, which is achieved by driving the shutdown pin with a logic low. Additionally, the SGM4891 features an internal thermal shutdown protection mechanism.

The SGM4891 does not require output coupling capacitors or bootstrap capacitors, and therefore is ideally suited for mobile phone and other low voltage applications where minimal power consumption is a primary requirement.

For maximum flexibility, the SGM4891 provides an externally controlled gain (with resistors), as well as an externally controlled turn-on time (with the bypass capacitor). When using a 1μF bypass capacitor, it offers 145ms wake-up time when V_+ is equal to 5.0V.

The SGM4891 is available in Green TDFN-2×2-8L package. It operates over an ambient temperature range of -40℃ to +85℃.

FEATURES

- **Ideal for Notebook Computers, PDAs, and Other Small Portable Audio Devices**
- **1.2W into 8Ω BTL Load from 5V Supply at THD+N = 1% (TYP)**
- **Excellent PSRR: Direct Connection to Battery**
- **Fast Turn-On Time**
- **Unity Gain Stable**
- **2.5V to 5.5V Operation**
- **Shutdown Current: 0.02μA (TYP)**
- **Shutdown Pin is Compatible with 1.8V Logic**
- **-40℃ to +85℃ Operating Temperature Range**
- **Available in Green TDFN-2×2-8L Package**

APPLICATIONS

Portable Systems
MP3 Players
Mobile Phone
PDAs
GPS

PACKAGE/ORDERING INFORMATION

ORDER NUMBER	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	PACKAGE OPTION	MARKING INFORMATION
SGM4891YDE8G/TR	TDFN-2×2-8L	-40℃ to +85℃	Tape and Reel, 3000	4891

ABSOLUTE MAXIMUM RATINGS

Supply Voltage……6V
Input Voltage……-0.3V to (V_+) + 0.3V
Storage Temperature Range……-65℃ to +150℃
Junction Temperature……150℃
Operating Temperature Range……-40℃ to +85℃
Lead Temperature Range (Soldering 10 sec)
……260℃
ESD Susceptibility
HBM……2000V
MM……200V

NOTE:
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

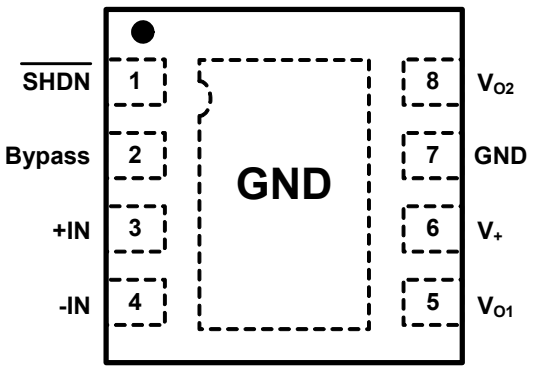
CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

SGMICRO reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time. Please contact SGMICRO sales office to get the latest datasheet.

PIN CONFIGURATION (TOP VIEW)

SGM4891YDE8G



TDFN-2×2-8L

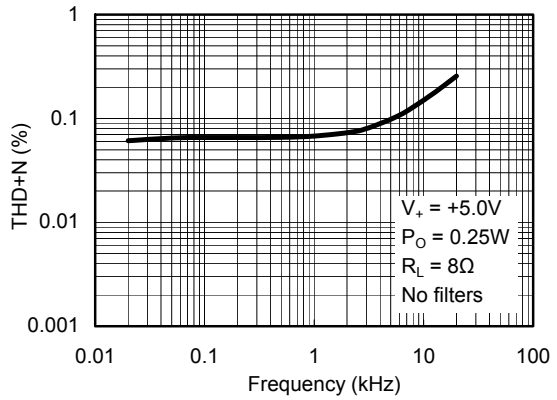
ELECTRICAL CHARACTERISTICS

(T_A = +25℃, unless otherwise specified.)

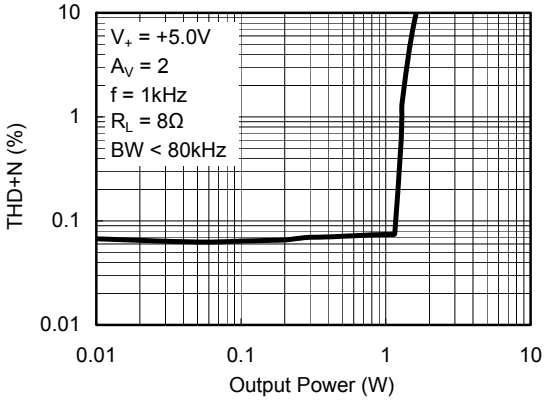
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Quiescent Power Supply Current	I_Q	V_{IN} = 0V, I_O = 0A	V_+ = +5.0V, No Load		5.45	10	mA
			V_+ = +5.0V, 8Ω Load		5.50	12	
			V_+ = +3.6V, No Load		5.10		
			V_+ = +3.6V, 8Ω Load		5.20		
			V_+ = +3.0V, No Load		5.00	8	
			V_+ = +3.0V, 8Ω Load		5.10	10.5	
			V_+ = +2.6V, No Load		4.70		
			V_+ = +2.6V, 8Ω Load		4.75		
Shutdown Current	I_{SD}	$V_{SHUTDOWN}$ = 0V			0.02	2	μA
Shutdown Voltage Input High	V_{SDIH}			1.2			V
Shutdown Voltage Input Low	V_{SDIL}					0.4	V
Output Offset Voltage	V_{OS}			-65	1	65	mV
Output Power (8Ω)	P_O	f = 1kHz, THD+N = 1%	V_+ = +5.0V		1.2		W
			V_+ = +3.6V		0.6		
			V_+ = +3.0V		0.4		
			V_+ = +2.6V		0.3		
		f = 1kHz, THD+N = 10%	V_+ = +5.0V		1.5		
			V_+ = +3.6V		0.8		
			V_+ = +3.0V		0.5		
			V_+ = +2.6V		0.4		
Total Harmonic Distortion + Noise	THD+N	P_O = 0.4Wrms, f = 1kHz			0.07		%
Power Supply Rejection Ratio	PSRR	f = 217Hz	V_+ = +5.0V		68		dB
			V_+ = +3.6V		68		
			V_+ = +3.0V		68		
			V_+ = +2.6V		67		
		f = 1kHz	V_+ = +5.0V		72		
			V_+ = +3.6V		72		
			V_+ = +3.0V		71		
			V_+ = +2.6V		70		
Wake-Up Time	T_{WU}	C_{BYPASS} = 1μF	V_+ = +5.0V		145		ms

TYPICAL PERFORMANCE CHARACTERISTICS

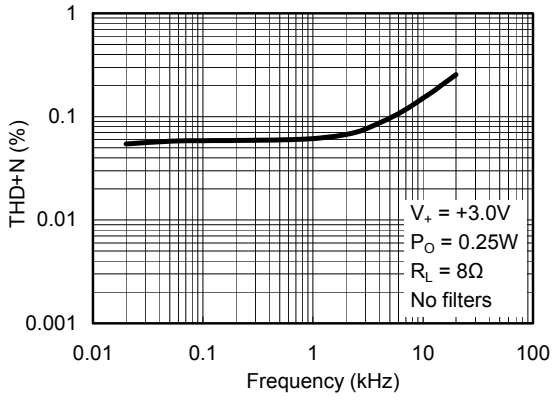
THD+N vs. Frequency



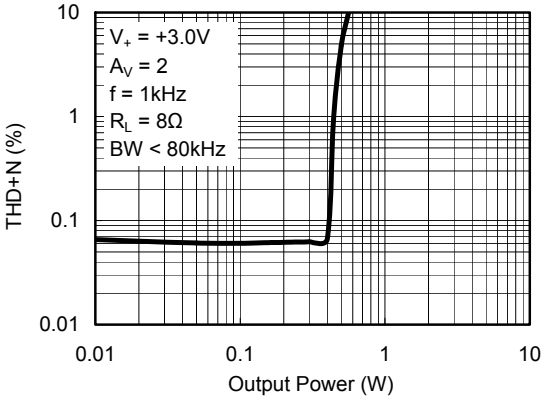
THD+N vs. Output Power



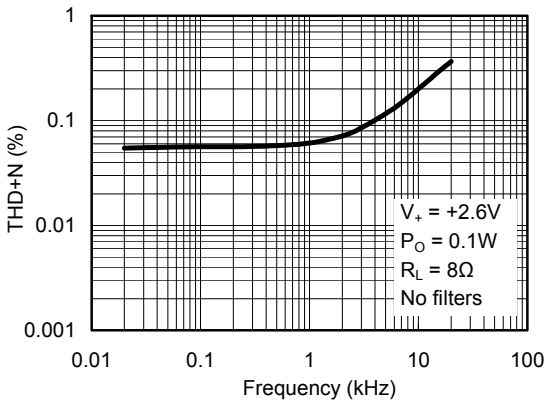
THD+N vs. Frequency



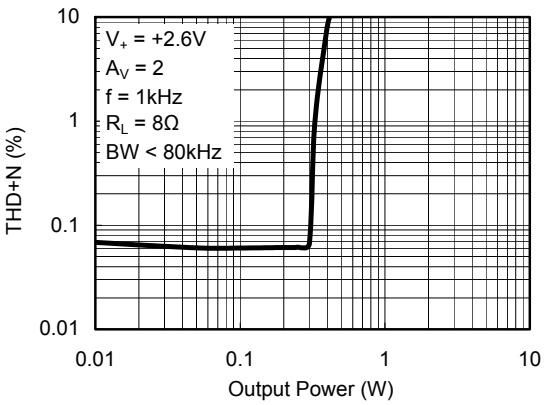
THD+N vs. Output Power



THD+N vs. Frequency

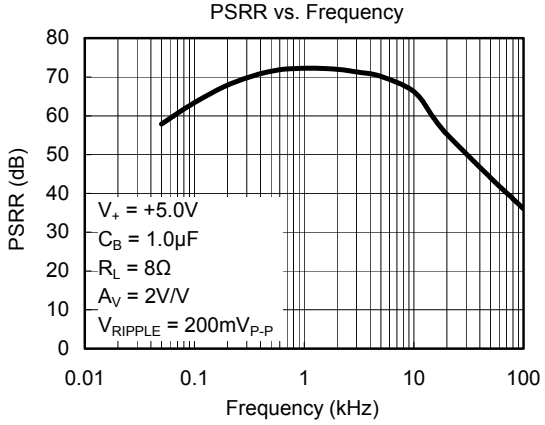


THD+N vs. Output Power

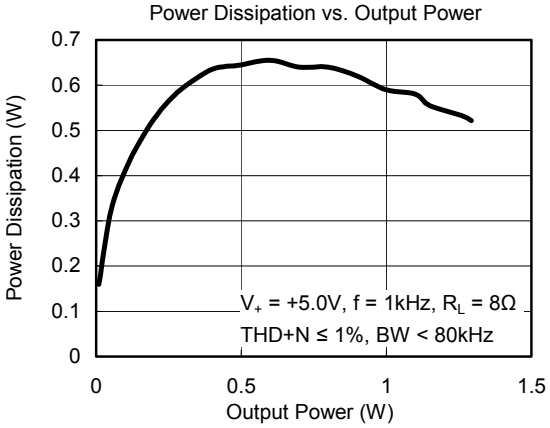


TYPICAL PERFORMANCE CHARACTERISTICS

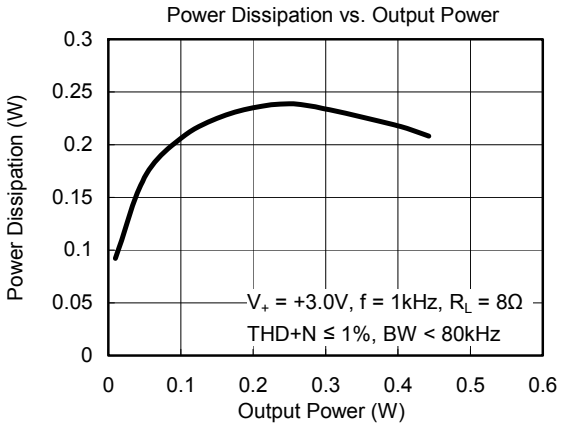
PSRR vs. Frequency



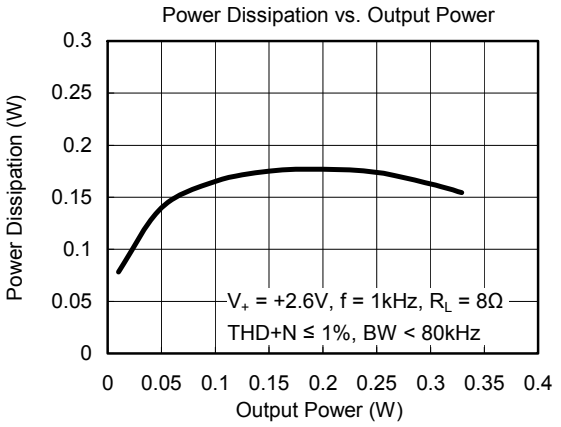
Power Dissipation vs. Output Power



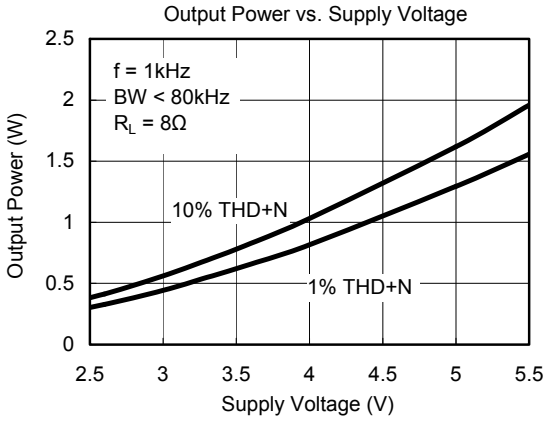
Power Dissipation vs. Output Power



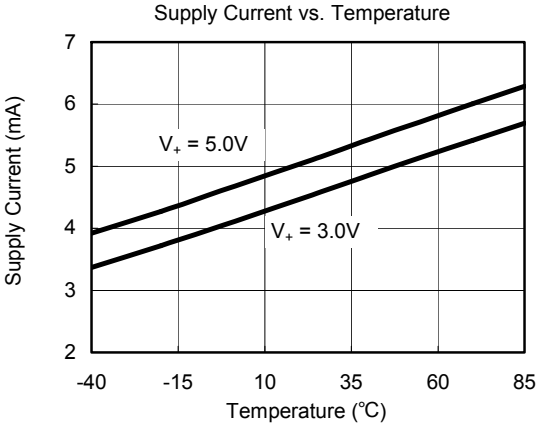
Power Dissipation vs. Output Power



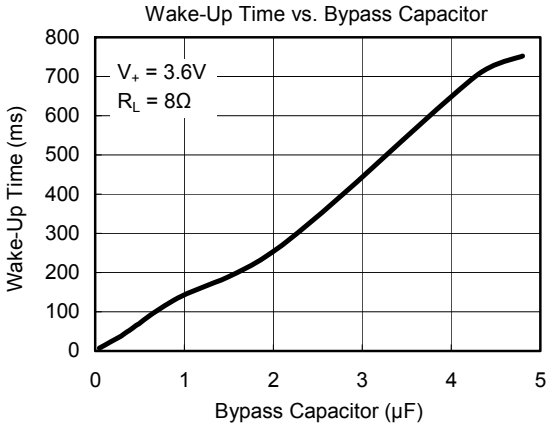
Output Power vs. Supply Voltage



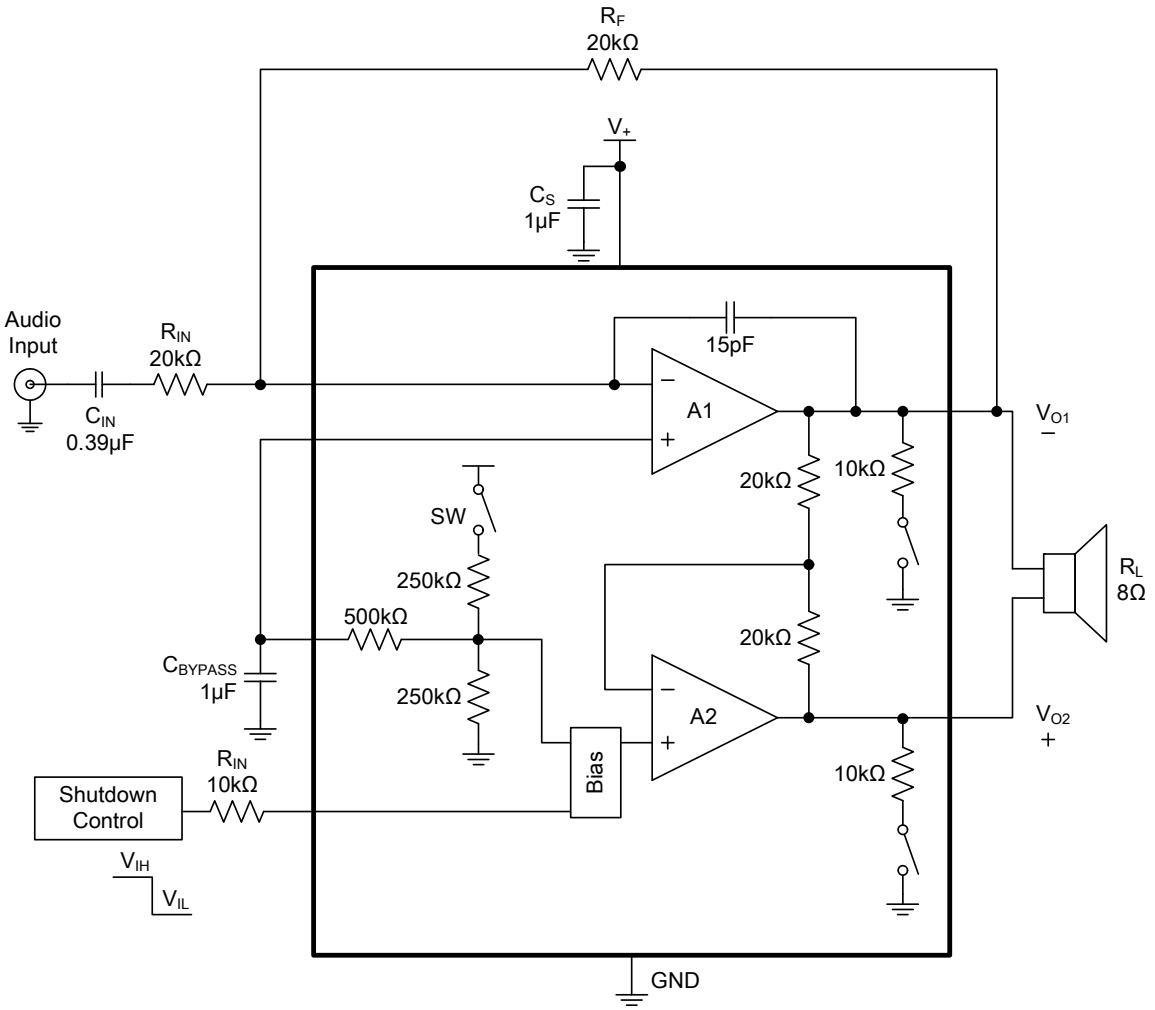
Supply Current vs. Temperature



TYPICAL PERFORMANCE CHARACTERISTICS



TYPICAL APPLICATION



NOTE:
1. A 10kΩ resistor must be serially connected to $\overline{SHDN}$ pin.

APPLICATION NOTES

PCB Design Recommendations (Thermal Design Considerations)

Thermal Land

The TDFN-2×2-8L thermal land is a metal (normally copper) region centrally located under the package and on top of the PCB. It has a rectangular or square shape and should match the dimensions of the exposed pad on the bottom of the package (1:1 ratio).

For certain high power applications, the PCB land may be modified to a "dog bone" shape that enhances thermal performance. The packages used with the "dog bone" lands will be a dual inline configuration (see Figure 1).

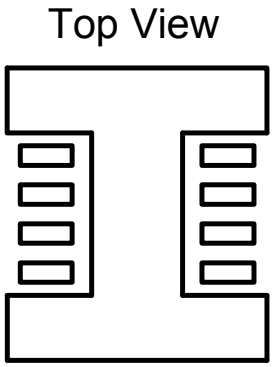


Figure 1. Dog Bone

Thermal Vias

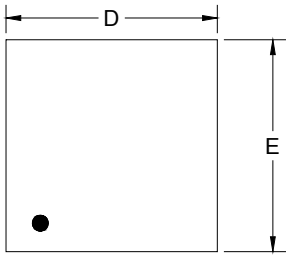
Thermal vias are necessary. They conduct heat from the exposed pad of the package to the ground plane. The number of vias is application specific and is dependent upon electrical requirements and power dissipation.

The via diameter should be 0.2mm to 0.33mm with 1oz. copper via barrel plating. It is important to plug the via to avoid any solder wicking inside the via during the soldering process. The thermal vias can be tented with solder mask on the top surface of the PCB. The solder mask diameter should be at least 75microns (or 3mils) larger than the via diameter. The solder mask thickness should be the same across the entire PCB.

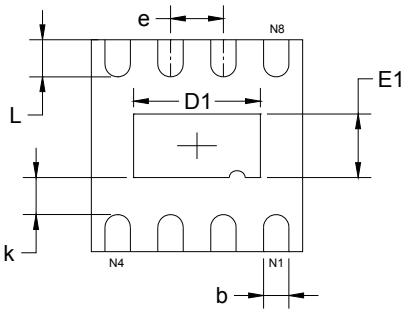
A package thermal performance may be improved by increasing the number of vias.

PACKAGE OUTLINE DIMENSIONS

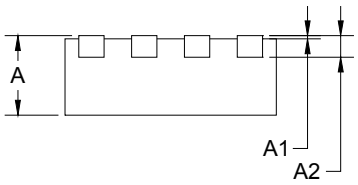
TDFN-2×2-8L



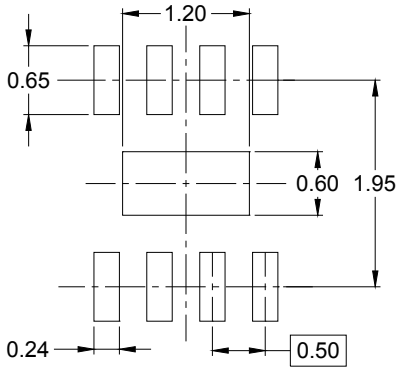
TOP VIEW



BOTTOM VIEW



SIDE VIEW

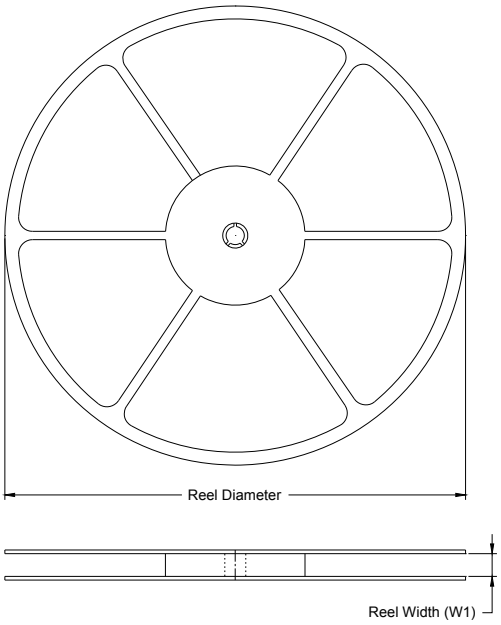


RECOMMENDED LAND PATTERN (Unit: mm)

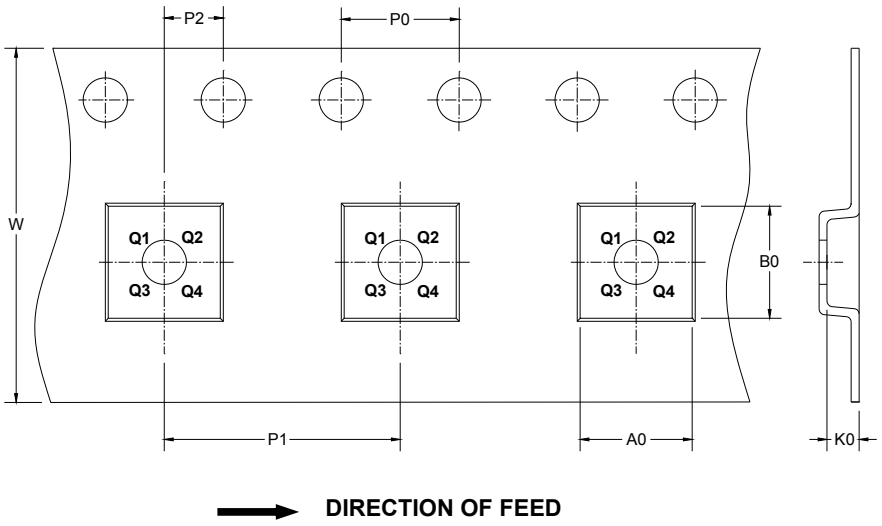
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	1.900	2.100	0.075	0.083
D1	1.100	1.300	0.043	0.051
E	1.900	2.100	0.075	0.083
E1	0.500	0.700	0.020	0.028
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.500 TYP		0.020 TYP	
L	0.250	0.450	0.010	0.018

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS

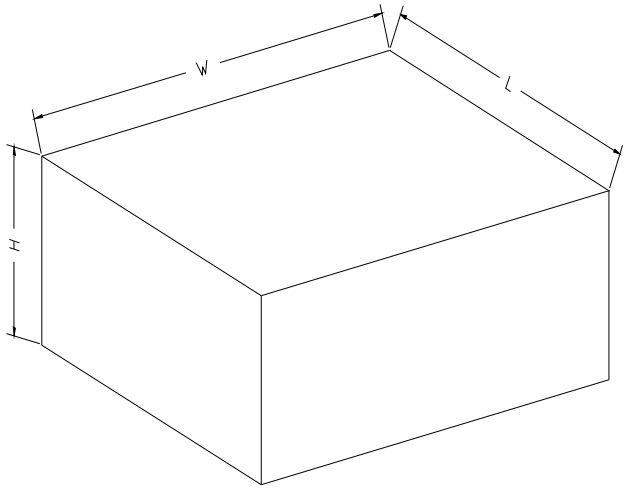


NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-2×2-8L	7″	9.5	2.30	2.30	1.10	4.00	4.00	2.00	8.00	Q1

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7″ (Option)	368	227	224	8
7″	442	410	224	18